

Feature:

- Water transparent
- Package in bulk and tape and reel
- High radiant intensity
- Peak wavelength 850nm
- AlGaAs technology
- 30deg emitting angle

Description:

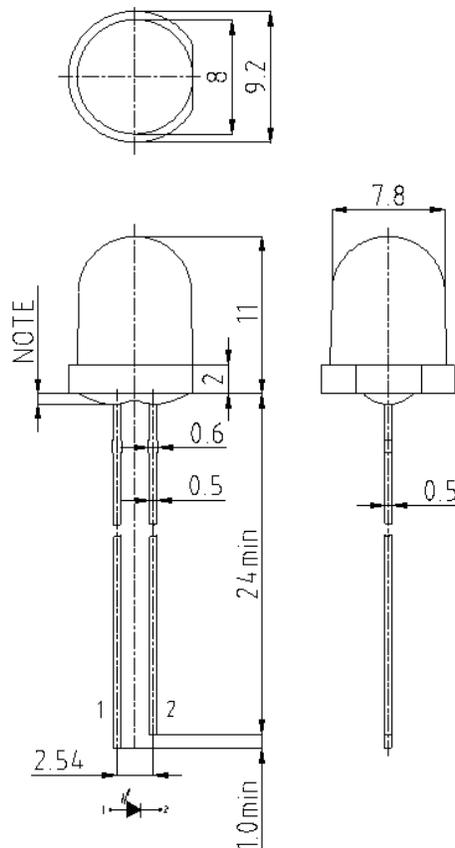
This device is spectrally match with phototransistor, photodiode, and infrared receiver module

Application:

- Infrared illumination
- Telecommunication system
- Infrared applied system
- Sensor application

Certification & Compliance:

- TS16949
- ISO9001
- RoHS Compliant

**Dimension:**

Units: mm / tolerance = +/-0.1mm

Electrical / Optical Characteristic (T=25 °C)

Product	I _F (mA)	V _F (V)		λ _P (nm)			I _e (mW/sr)	
		Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.
QBED9345	50	1.5	2.2	820	850	880	37.2	100

Absolute Maximum Rating

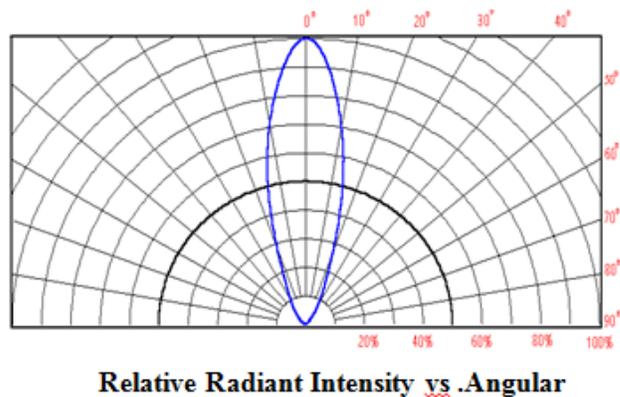
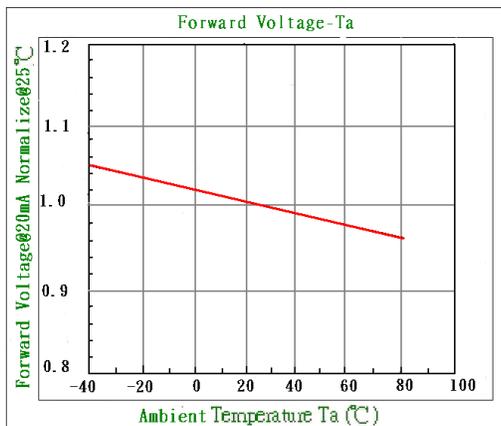
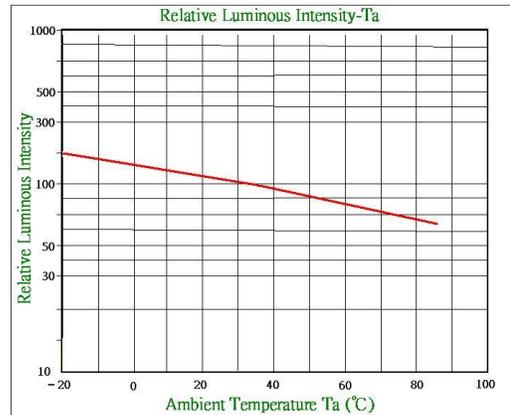
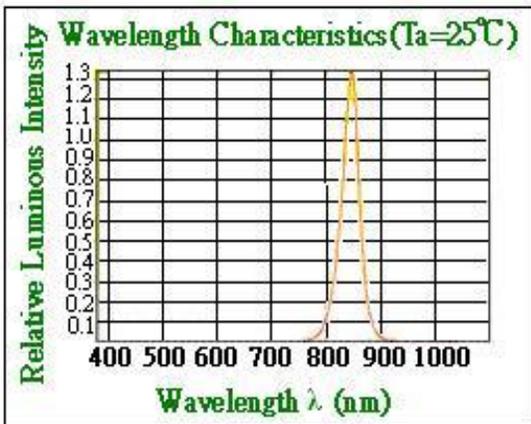
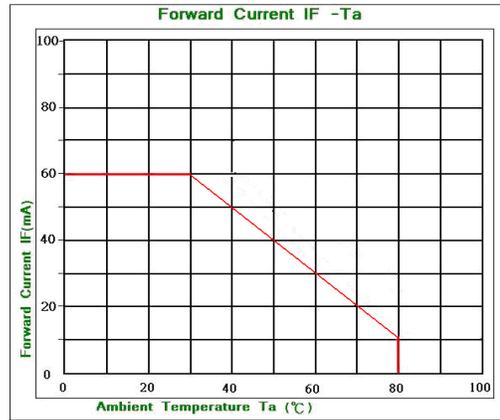
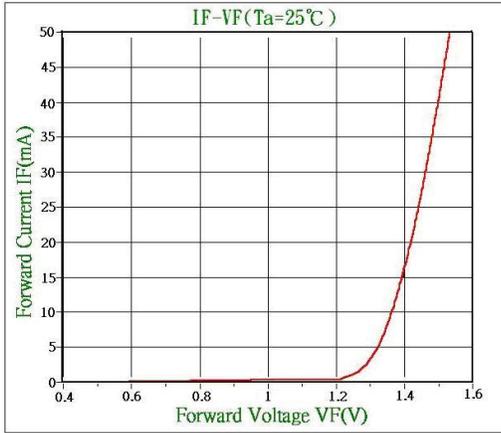
Material	P _d (mW)	I _F (mA)	I _{FP} (mA)*	V _R (V)	T _{OP} (°C)	T _{ST} (°C)	T _{SOL} (°C)**
AlGaAs	150	70	100	5	-40 ~ +80	-40 ~ +100	260

*Duty 1/10 @ 10KHz

** IR Reflow for no more than 10 sec @ 260 °C

Characteristic Curves:

AlGaAs Material

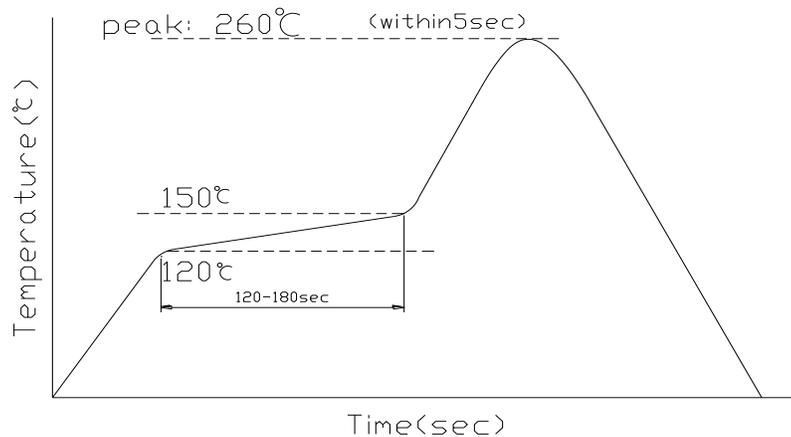


Solder Profile & Footprint:

A. Soldering

1. When soldering, the soldering iron needs to be at least 2mm away from the epoxy edge. After soldering, allow at least 3 minutes for LEDs to cool back to normal temperature. Do not apply any pressure to the epoxy encapsulation or the lead frame during the soldering process.
2. When reflow soldering or wave soldering, please solder once for less than 5 seconds at a maximum temperature of 260°C. During the soldering process, if the temperature or timing is not controlled within limits, it would cause the epoxy to deform or cause the die or wires within the LED to be damaged.

WAVE SOLDERING PROFILE FOR LEAD FREE PROCESS:



3. When using soldering iron, please solder once for less than 5 seconds at a maximum temperature of 300°C. When soldering a row of LED on a PCB, please do not solder both leads of a LED in sequence. (Solder all the positive lead first, then all the negative

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leads)

4. Do not dip the epoxy encapsulation part of LED into any soldering paste liquid.
5. After soldering, do not adjust the location of the LED anymore.

When attaching electronic parts to a PCB with LEDs, the curing time for the whole PCB should be less than 60 seconds, at less than a temperature of 120

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Labeling:

Part No: _____

Customer P/N: _____

Item: _____

Q'ty: _____

Vf: _____

Iv: _____

WI: _____

Date: _____

Made in China**Ordering Information:**

Part #	Orderable Part #	Spec Range	Quantity per reel
QBED9330	QBED9330	Ie = 100mW/sr @ 50mA, λ_p = 850nm	TBD

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Revision History:

Description:	Revision #	Revision Date
New Release of QBED9330	V1.0	06/25/2011